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## STPSC1206

### 600 V power Schottky silicon carbide diode

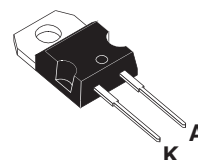
#### Features

- No reverse recovery
- Switching behavior independent of temperature
- Dedicated to PFC boost diode

#### Description

These diodes are manufactured using silicon carbide substrate. This wide bandgap material supports the manufacture of a Schottky diode structure with a high voltage rating. Such diodes exhibit no or negligible recovery characteristics. The recovery characteristics are independent of the temperature.

Using these diodes will significantly reduce the switching power losses of the associated MOS-FET, and thus increase the efficiency of the overall application. These diodes will then outperform the power factor correction circuit operating in hard switching conditions.



**TO-220AC**  
**STPSC1206D**

**Table 1. Device summary**

$I_{F(AV)}$	12 A
$V_{RRM}$	600 V
$T_j (max)$	175 °C
$Q_C (typ)$	12 nC

## Characteristics

STPSC1206

# 1 Characteristics

**Table 2. Absolute ratings (limiting values at 25 °C unless otherwise specified)**

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		600	V
$I_{F(RMS)}$	Forward rms current		30	A
$I_{F(AV)}$	Average forward current	$T_c = 110\text{ °C}, \delta = 0.5$	12	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10\text{ ms sinusoidal}, T_c = 25\text{ °C}$	50	A
		$t_p = 10\text{ ms sinusoidal}, T_c = 125\text{ °C}$	40	
		$t_p = 10\text{ }\mu\text{s square}, T_c = 25\text{ °C}$	200	
$I_{FRM}$	Repetitive peak forward current	$T_c = 105\text{ °C}, T_j = 150\text{ °C}, \delta = 0.1$	50	A
$T_{stg}$	Storage temperature range		-55 to +175	°C
$T_j$	Operating junction temperature		-40 to +175	°C

**Table 3. Thermal resistance**

Symbol	Parameter	Maximum value	Unit
$R_{th(j-c)}$	Junction to case	1.75	°C/W

**Table 4. Static electrical characteristics**

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-	30	150	$\mu\text{A}$
		$T_j = 150\text{ °C}$		-	200	1500	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 12\text{ A}$	-	1.4	1.7	V
		$T_j = 150\text{ °C}$		-	1.6	2.1	

1.  $t_p = 10\text{ ms}, \delta < 2\%$

2.  $t_p = 500\text{ }\mu\text{s}, \delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 1.2 \times I_{F(AV)} + 0.075 \times I_{F(RMS)}^2$$

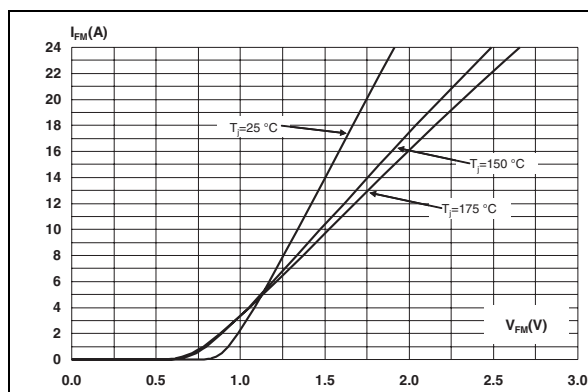
**Table 5. Other parameters**

Symbol	Parameter	Test conditions	Typ.	Unit
$Q_c$	Total capacitive charge	$V_r = 400\text{ V}, I_F = 12\text{ A}$ $di_F/dt = -200\text{ A}/\mu\text{s}, T_j = 150\text{ °C}$	12	nC
C	Total capacitance	$V_r = 0\text{ V}, T_c = 25\text{ °C}, F = 1\text{ Mhz}$	750	pF
		$V_r = 400\text{ V}, T_c = 25\text{ °C}, F = 1\text{ Mhz}$	65	

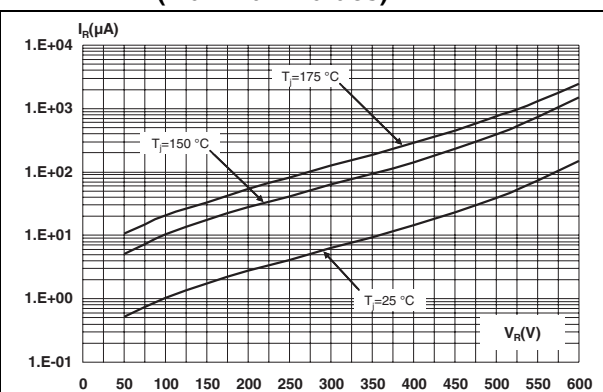
**STPSC1206**

**Characteristics**

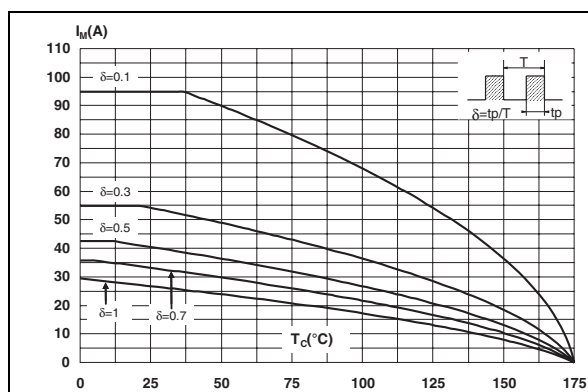
**Figure 1. Forward voltage drop versus forward current (typical values)**



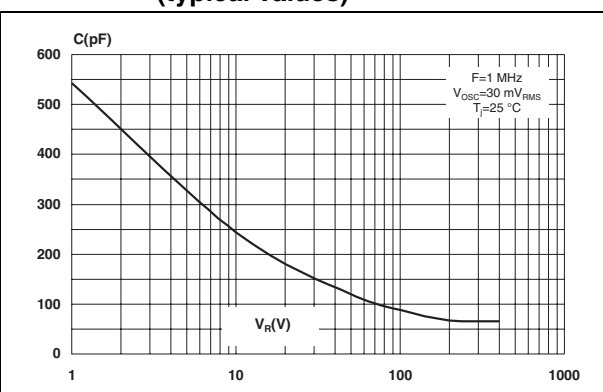
**Figure 2. Reverse leakage current versus reverse voltage applied (maximum values)**



**Figure 3. Peak forward current versus case temperature**



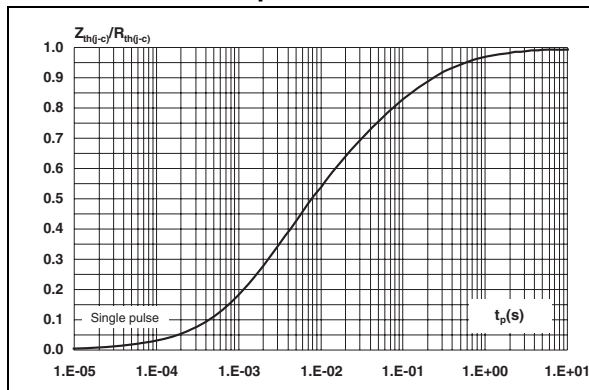
**Figure 4. Junction capacitance versus reverse voltage applied (typical values)**



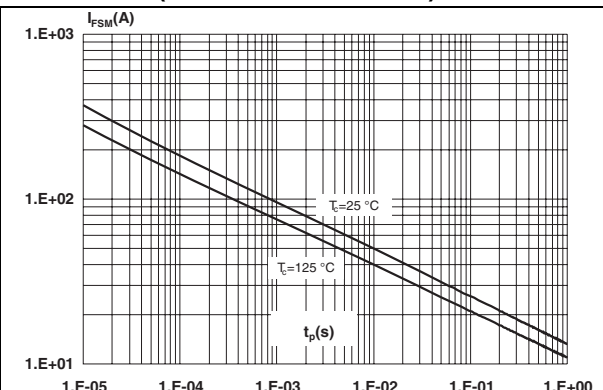
## Characteristics

STPSC1206

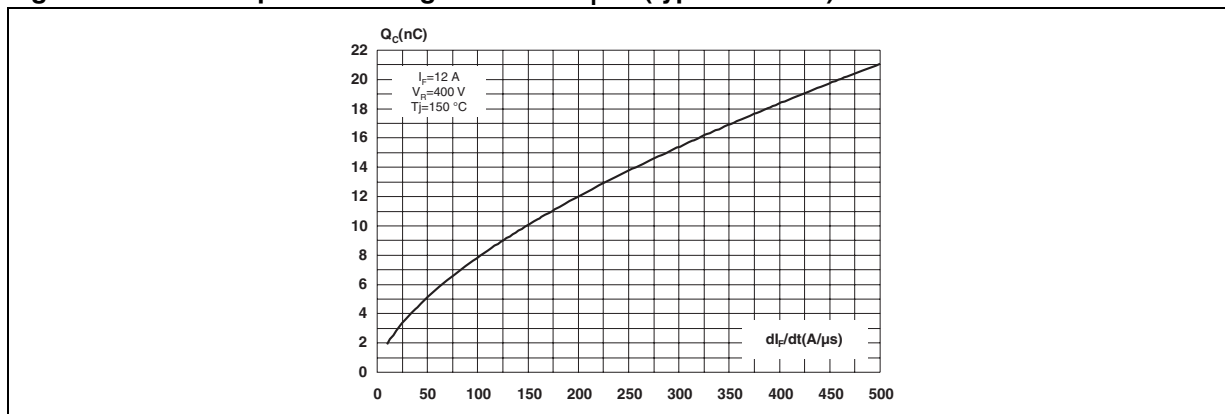
**Figure 5. Relative variation of thermal impedance junction to case versus pulse duration**



**Figure 6. Non-repetitive peak surge forward current versus pulse duration (sinusoidal waveform)**



**Figure 7. Total capacitive charges versus  $di_F/dt$  (typical values)**



**STPSC1206**

**Package information**

## 2 Package information

- Epoxy meets UL94, V0
- Colling method: convection (C)
- Recommended torque: 0.4 to 0.6 N·m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK<sup>®</sup> is an ST trademark.

**Table 6. TO-220AC dimensions**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam. I	3.75	3.85	0.147	0.151

## Ordering information

STPSC1206

### 3 Ordering information

**Table 7. Ordering information**

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPSC1206D	STPSC1206D	TO-220AC	1.86 g	50	Tube

### 4 Revision history

**Table 8. Document revision history**

Date	Revision	Changes
28-Sep-2009	1	First issue.

## STPSC1206

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